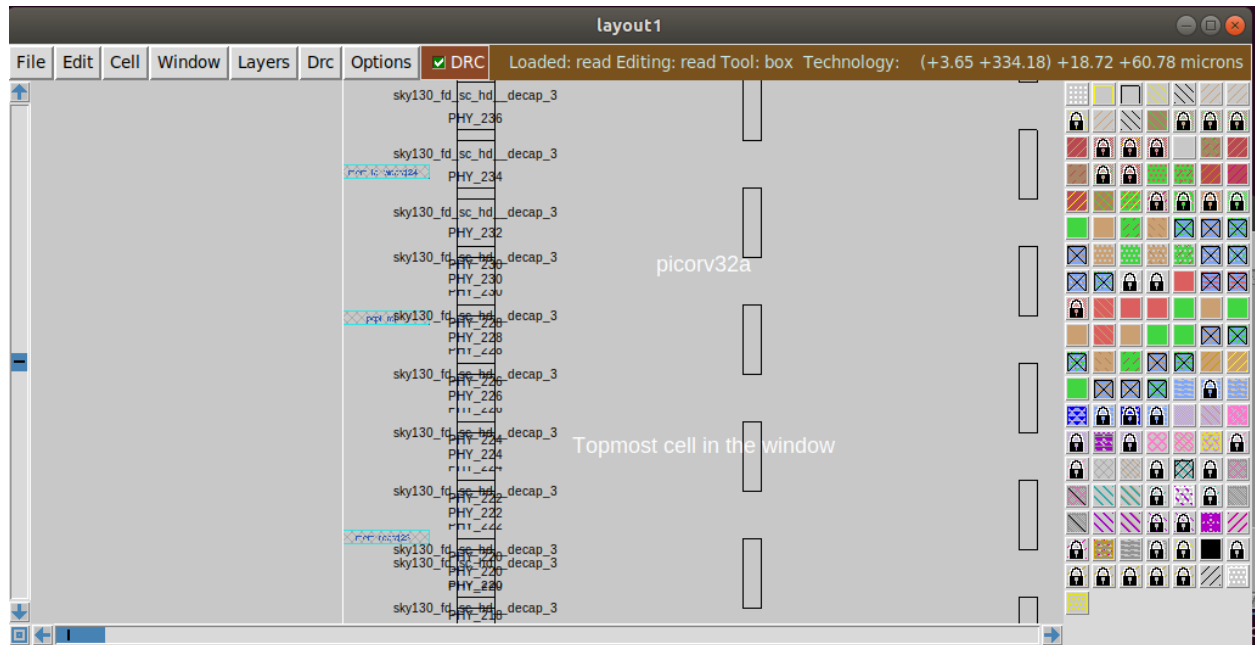
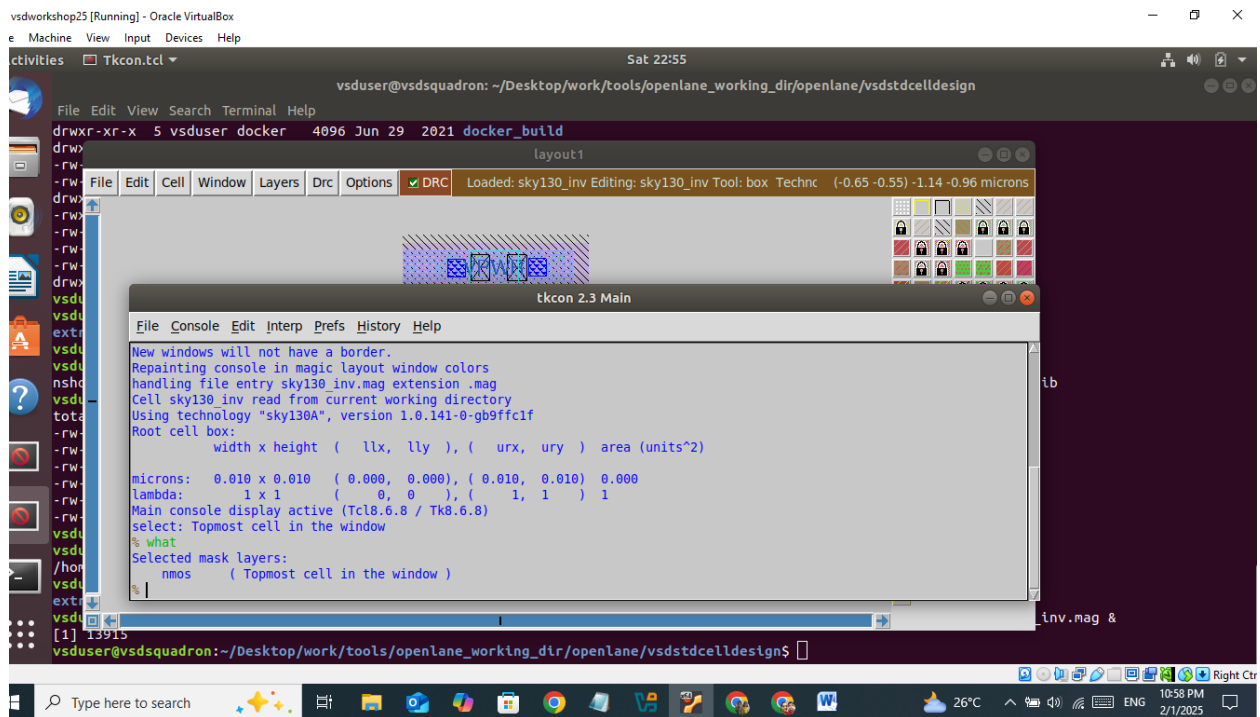
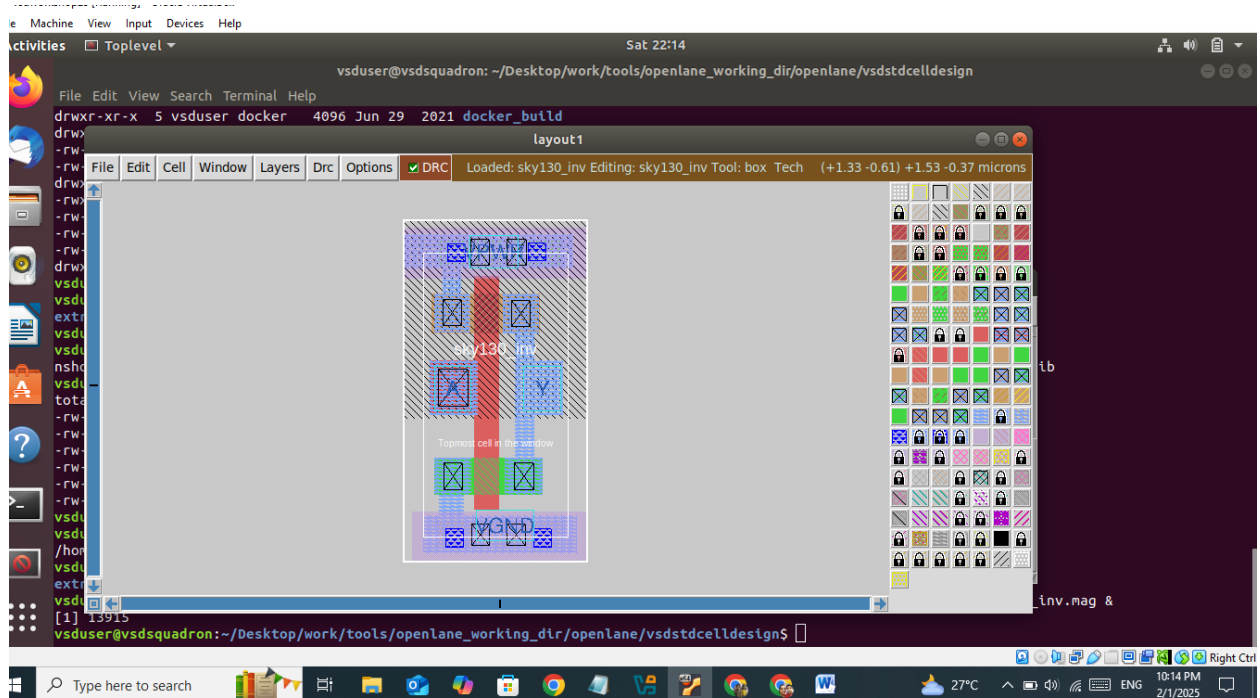


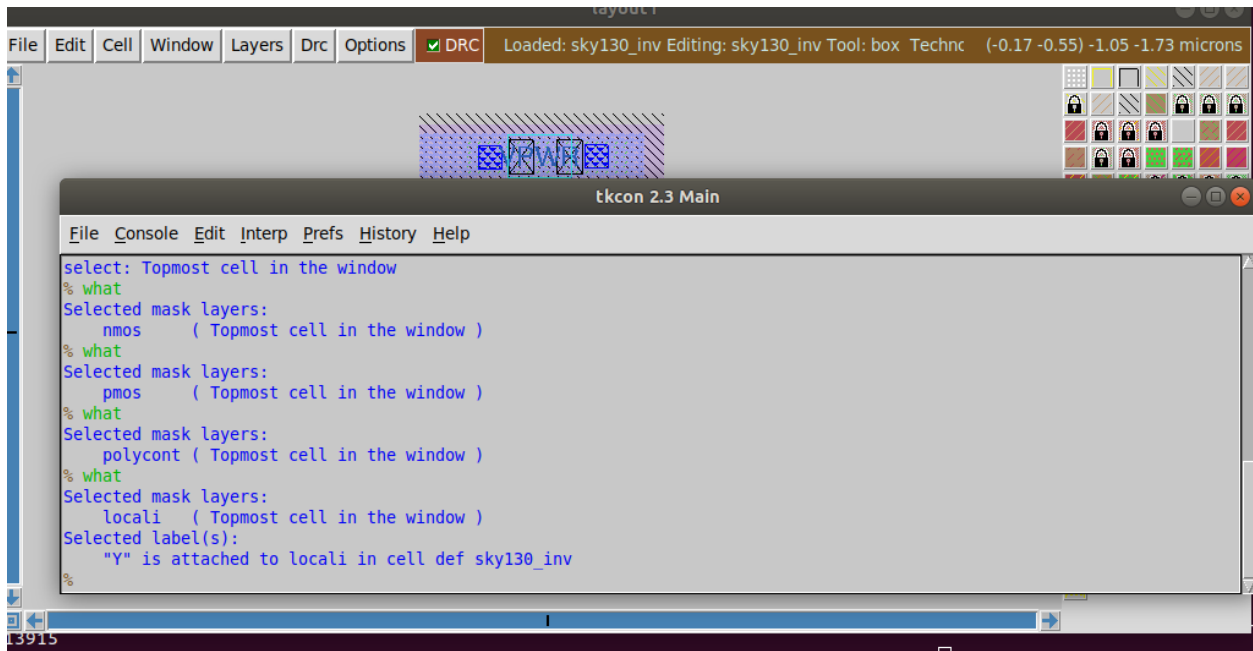
Day 3

Lab



```
vscuser@vscsquadron: ~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign
File Edit View Search Terminal Help
drwxr-xr-x 44 vscuser docker 4096 Jun 29 2021 designs
-rw-r--r-- 1 vscuser docker 1285 Jun 29 2021 CONTRIBUTING.md
-rw-r--r-- 1 vscuser docker 5514 Jun 29 2021 conf.py
drwxr-xr-x 2 vscuser docker 4096 Jun 29 2021 configuration
-rwxr-xr-x 1 vscuser docker 966 Jun 29 2021 clean_runs.tcl
-rw-r--r-- 1 vscuser docker 709 Jun 29 2021 AUTHORS.md
-rw-r--r-- 1 vscuser vscuser 963 May 20 2023 default.cvcrc
-rw-r--r-- 1 vscuser docker 25522 Feb 1 09:39 README.md
vscuser@vscsquadron:~/Desktop/work/tools/openlane_working_dir/openlane$ git clone https://github.com/nickson-jose/vsdstdcelldesign.git
Cloning into 'vsdstdcelldesign'...
remote: Enumerating objects: 492, done.
remote: Counting objects: 100% (18/18), done.
remote: Compressing objects: 100% (18/18), done.
remote: Total 492 (delta 7), reused 0 (delta 0), pack-reused 474 (from 1)
Receiving objects: 100% (492/492), 24.08 MiB | 6.71 MiB/s, done.
Resolving deltas: 100% (210/210), done.
vscuser@vscsquadron:~/Desktop/work/tools/openlane_working_dir/openlane$ ls -lrt
total 140
drwxr-xr-x 15 vscuser docker 4096 Jun 29 2021 scripts
-rw-r--r-- 1 vscuser docker 20787 Jun 29 2021 run_designs.py
-rw-r--r-- 1 vscuser docker 7898 Jun 29 2021 report_generation_wrapper.py
drwxr-xr-x 3 vscuser docker 4096 Jun 29 2021 regression_results
-rw-r--r-- 1 vscuser docker 7273 Jun 29 2021 Makefile
-rw-r--r-- 1 vscuser docker 11350 Jun 29 2021 LICENSE
-rwxr-xr-x 1 vscuser docker 6519 Jun 29 2021 flow.tcl
drwxr-xr-x 5 vscuser docker 4096 Jun 29 2021 docs
drwxr-xr-x 5 vscuser docker 4096 Jun 29 2021 docker_build
drwxr-xr-x 44 vscuser docker 4096 Jun 29 2021 designs
-rw-r--r-- 1 vscuser docker 1285 Jun 29 2021 CONTRIBUTING.md
-rw-r--r-- 1 vscuser docker 5514 Jun 29 2021 conf.py
drwxr-xr-x 2 vscuser docker 4096 Jun 29 2021 configuration
-rwxr-xr-x 1 vscuser docker 966 Jun 29 2021 clean_runs.tcl
```






```

vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$ less sky130_inv.spice
vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$ vim sky130_inv.spice
vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$ cat sky130_inv.spice
* SPICE3 file created from sky130_inv.ext - technology: sky130A

.option scale=10n

.subckt sky130_inv A Y VPWR VGND
X0 Y A VGND VGND sky130_fd_pr__nfet_01v8 ad=1.43k pd=152 as=1.37k ps=148 w=3.5e+07 l=2.3e+07
X1 Y A VPWR VPWR sky130_fd_pr__pfet_01v8 ad=1.44k pd=152 as=1.52k ps=156 w=3.7e+07 l=2.3e+07
C0 VPWR A 0.0774f
C1 Y A 0.0754f
C2 VPWR Y 0.117f
C3 Y VGND 0.279f
C4 A VGND 0.45f
C5 VPWR VGND 0.781f
.ends
vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$ vim sky130_inv.spice
vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$

```

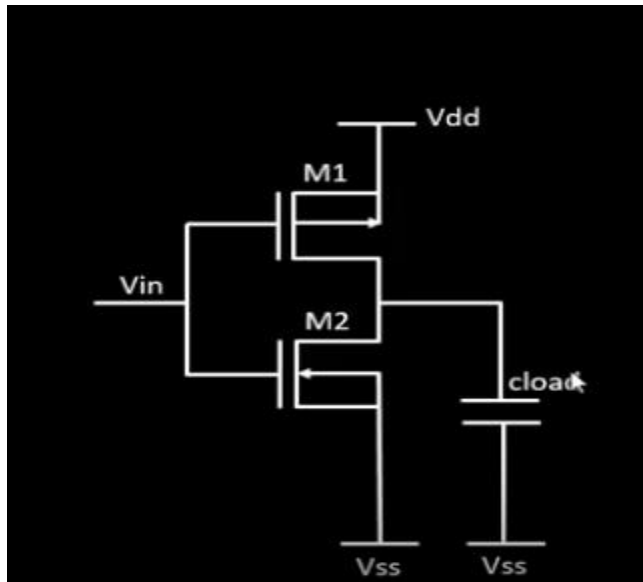
```

exttospace finished.
% box
Root cell box:
      width x height ( llx, lly ), ( urx, ury ) area (units^2)
microns:  0.170 x 0.200 ( 0.680, 1.430), ( 0.850, 1.630) 0.034
lambda:   17 x 20      ( 68, 143 ), ( 85, 163 ) 340
%
vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$ vim sky130_inv.spice
vdsuser@vdsquadron:~/Desktop/work/tools/openlane_working_dir/openlane/vsdstdcelldesign$

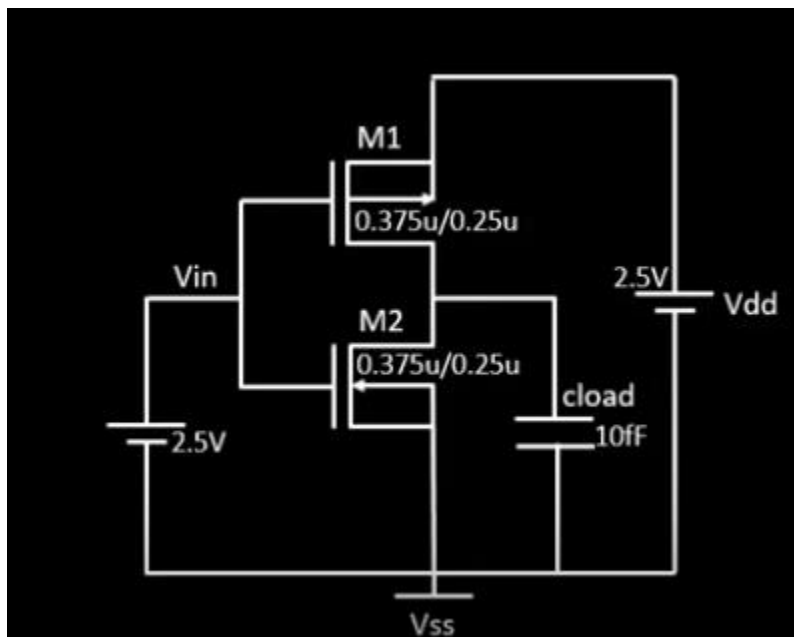
```

Spice deck

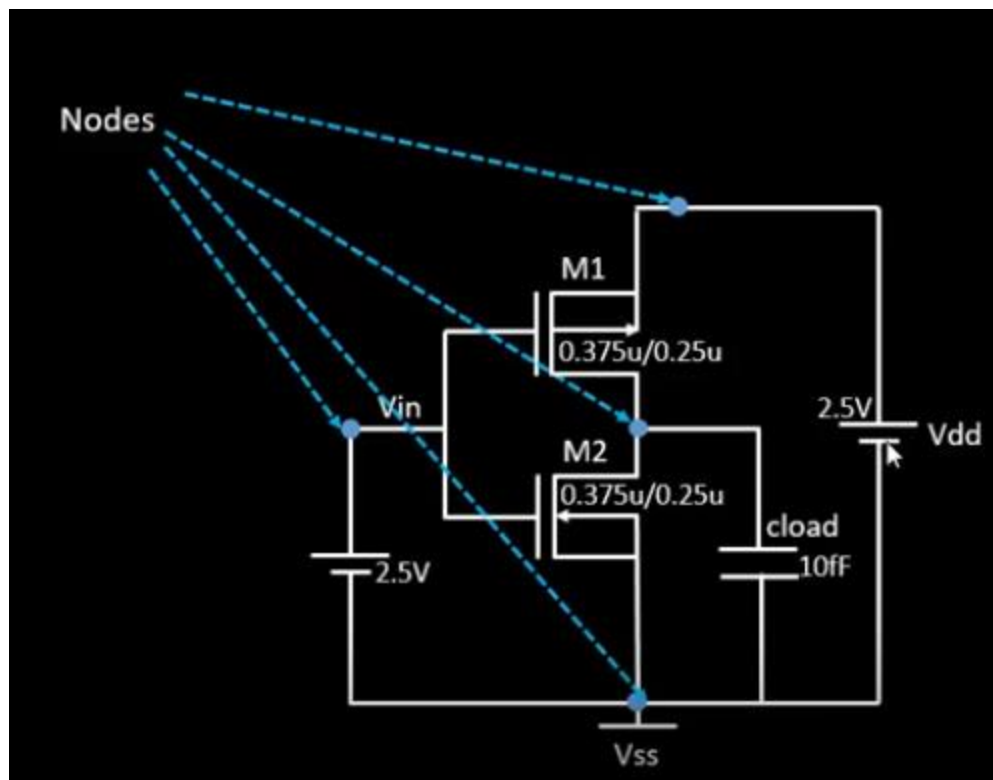
1)Component connectivity.



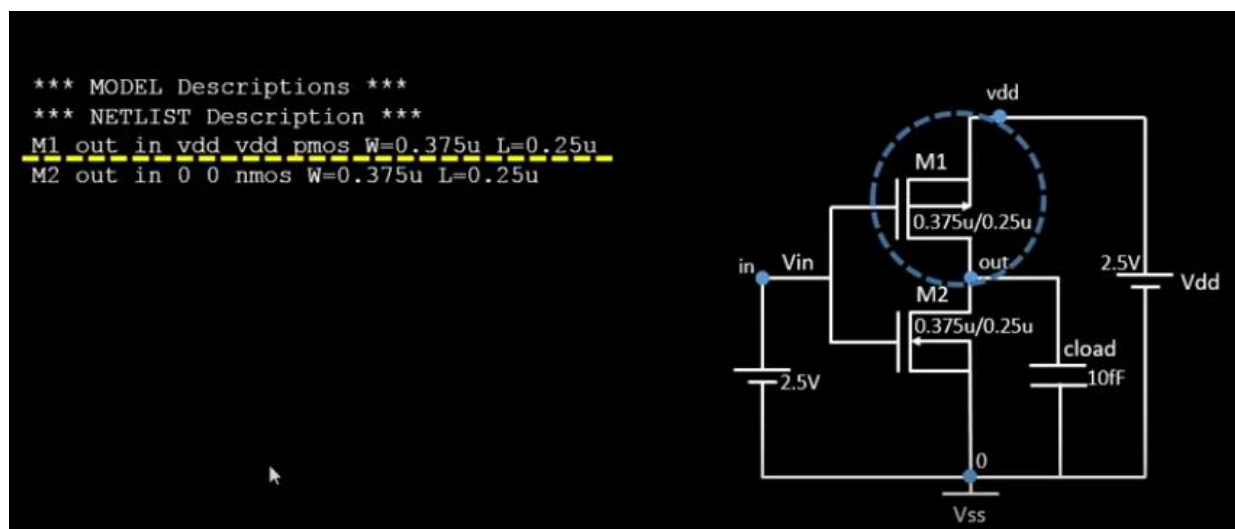
2)Component values



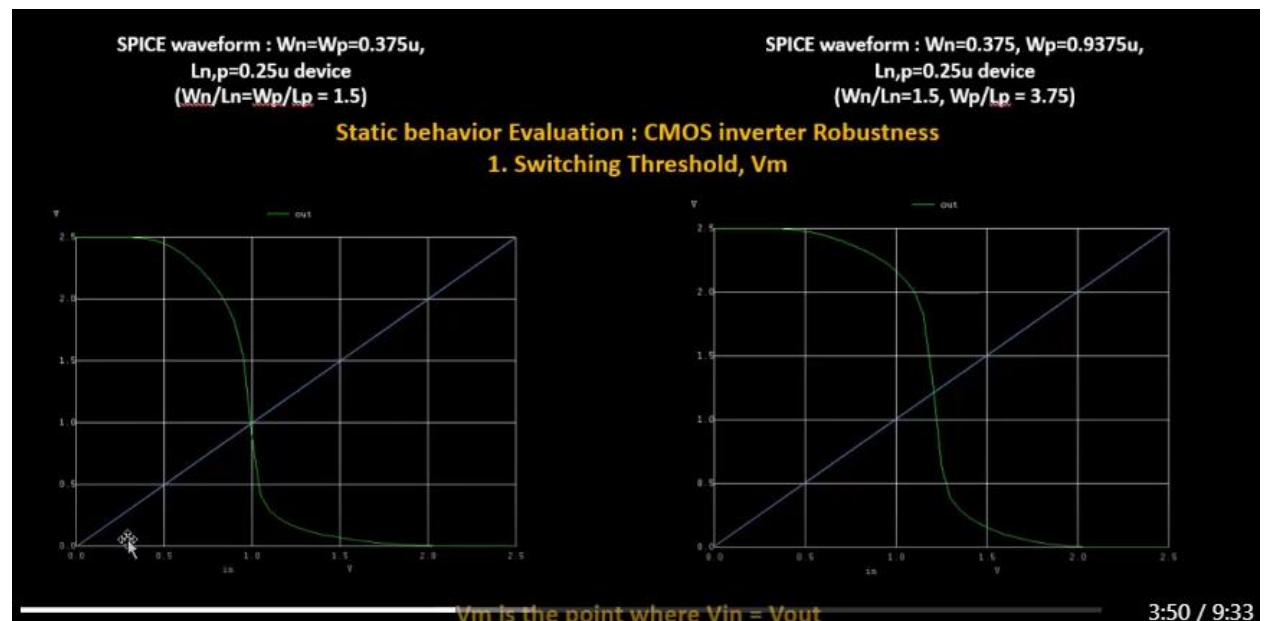
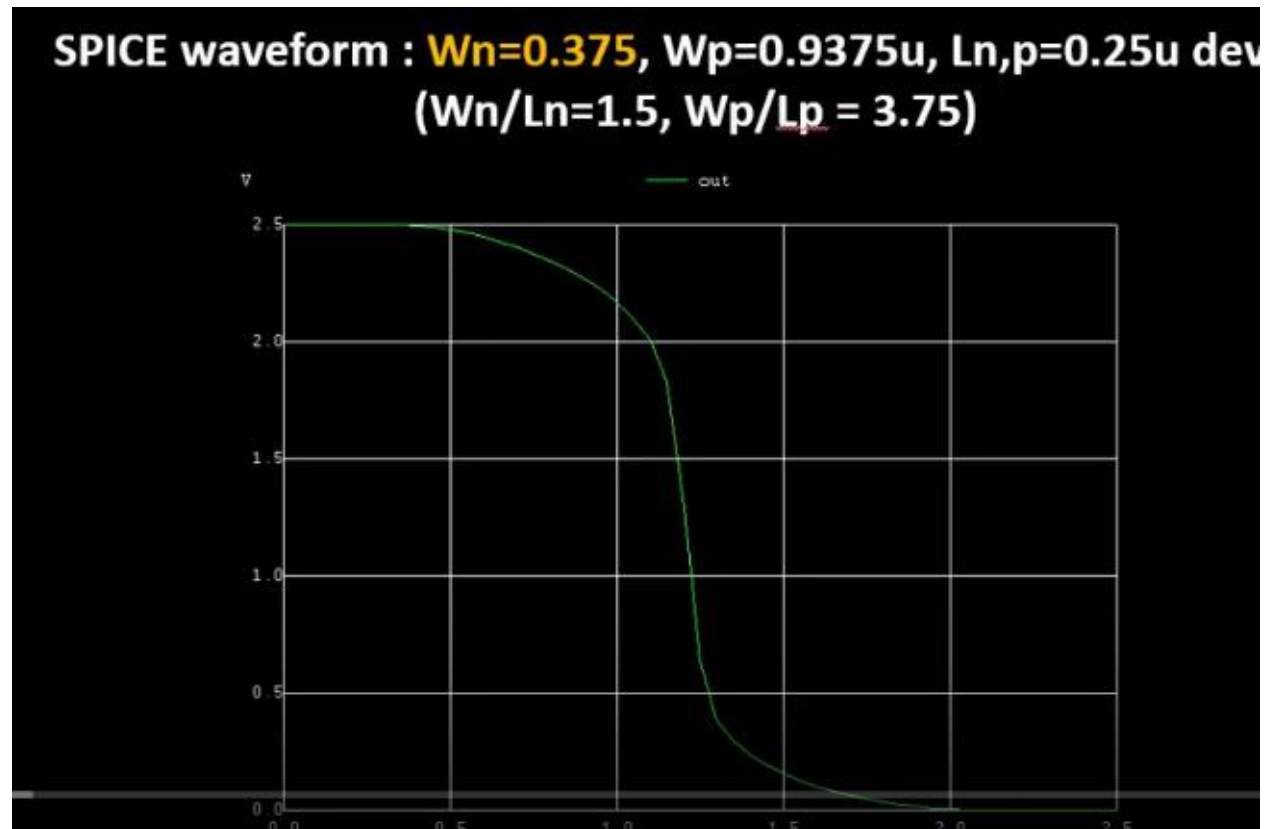
3)Identify nodes:



4) Name 'Nodes'



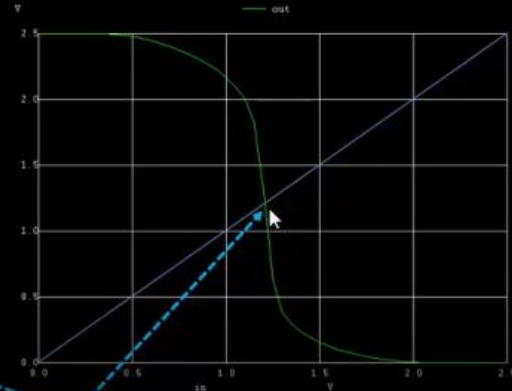
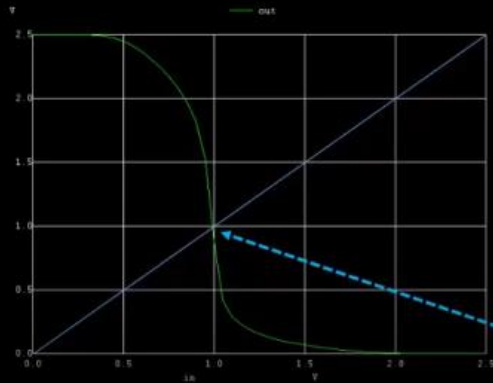
Spice waveform



SPICE waveform : $W_n=W_p=0.375\mu$,
 $L_n,p=0.25\mu$ device
 $(W_n/L_n=W_p/L_p = 1.5)$

SPICE waveform : $W_n=0.375$, $W_p=0.9375\mu$,
 $L_n,p=0.25\mu$ device
 $(W_n/L_n=1.5, W_p/L_p = 3.75)$

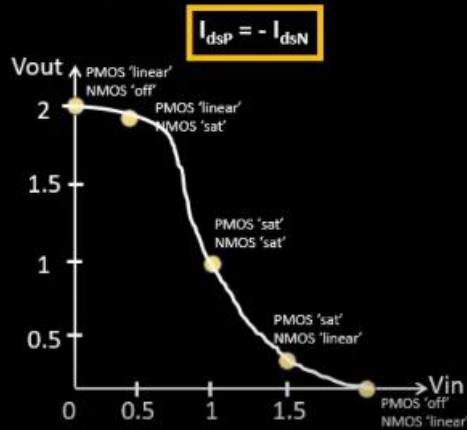
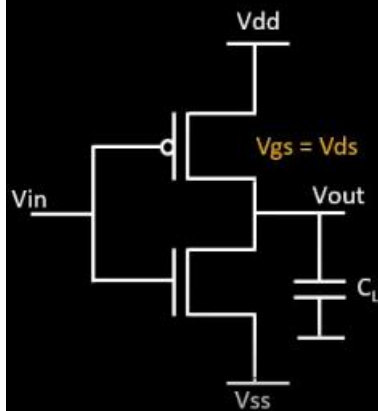
Static behavior Evaluation : CMOS inverter Robustness 1. Switching Threshold, V_m



SPICE waveform : $W_n=W_p=0.375\mu$,
 $L_n,p=0.25\mu$ device
 $(W_n/L_n=W_p/L_p = 1.5)$

SPICE waveform : $W_n=0.375$, $W_p=0.9375\mu$,
 $L_n,p=0.25\mu$ device
 $(W_n/L_n=1.5, W_p/L_p = 3.75)$

Static behavior Evaluation : CMOS inverter Robustness 1. Switching Threshold, V_m



$V_m \approx 0.98V$

V_m is the point where $V_{in} = V_{out}$

$V_m \approx 1.2V$

SPICE waveform : $W_n=W_p=0.375\mu$,
 $L_n,p=0.25\mu$ device
 $(W_n/L_n=W_p/L_p = 1.5)$

SPICE waveform : $W_n=0.375\mu$, $W_p=0.9375\mu$,
 $L_n,p=0.25\mu$ device
 $(W_n/L_n=1.5, W_p/L_p = 3.75)$

Static behavior Evaluation : CMOS inverter Robustness

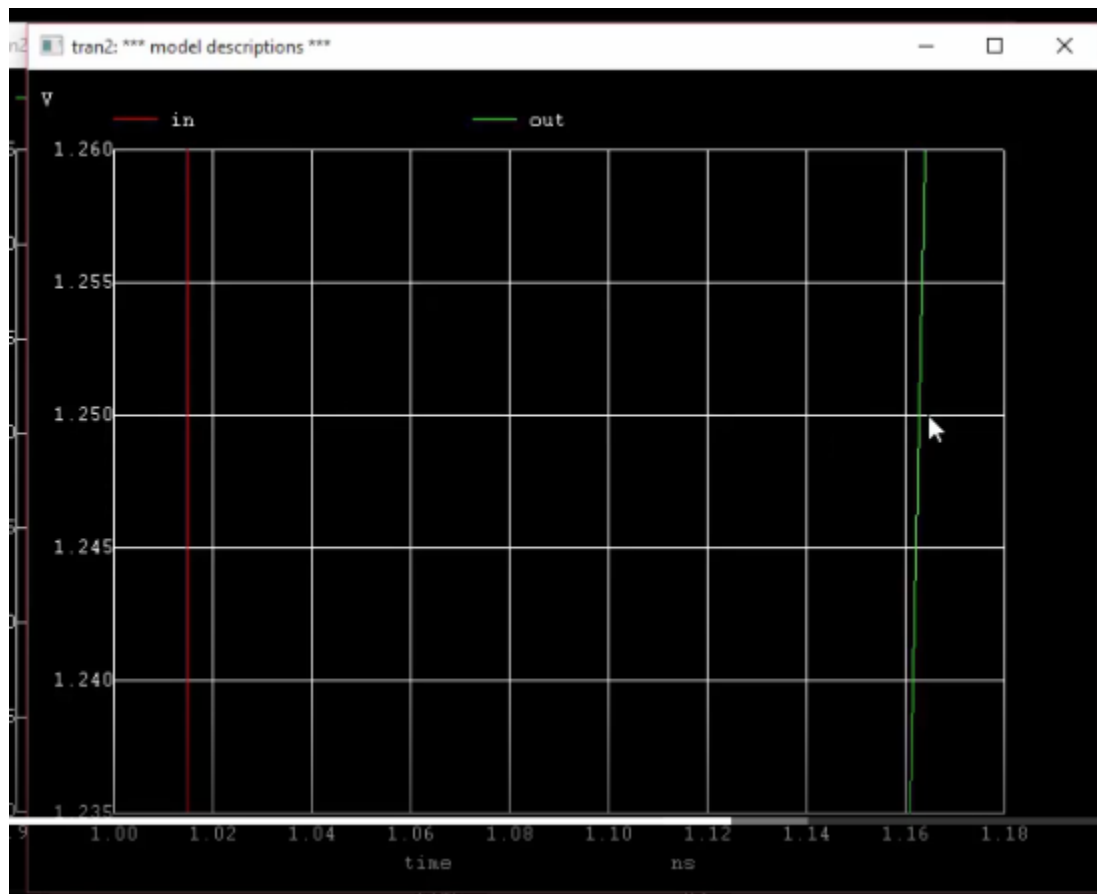
1. Switching Threshold, V_m

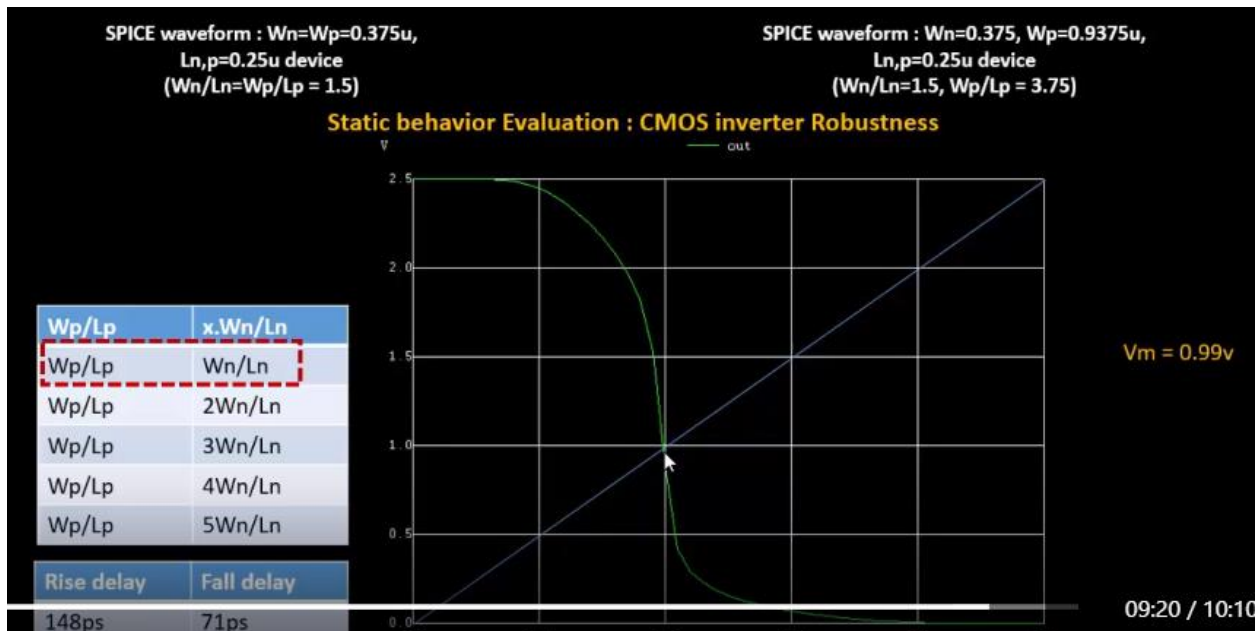
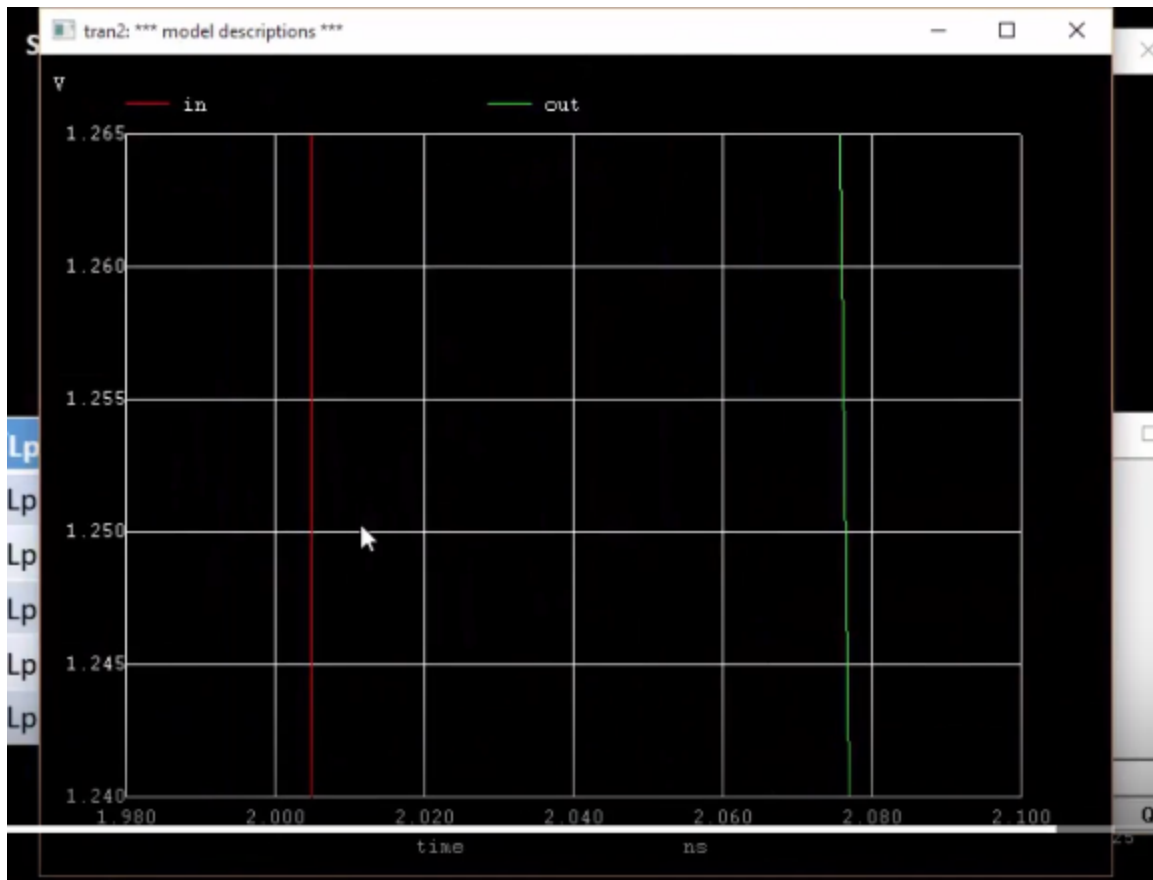
W_p/L_p	$x.W_n/L_n$
W_p/L_p	W_n/L_n
W_p/L_p	$2W_n/L_n$
W_p/L_p	$3W_n/L_n$
W_p/L_p	$4W_n/L_n$
W_p/L_p	$5W_n/L_n$

$$V_m = R \cdot V_{dd} / (1+R)$$

$$\text{Where } R = \frac{K_p \cdot V_{dsatp}}{K_n \cdot V_{dsatn}} = \frac{\left(\frac{W_p}{L_p}\right) K_{p'} \cdot V_{dsatp}}{\left(\frac{W_n}{L_n}\right) K_{n'} \cdot V_{dsatn}}$$

$$\frac{\left(\frac{W_p}{L_p}\right)}{\left(\frac{W_n}{L_n}\right)} = \frac{K_{n'} \cdot V_{dsatn}([V_m - V_t]) - \frac{V_{dsatn}^2}{2}}{K_{p'} \cdot V_{dsatp}([-V_m + V_{dd} + V_t]) + \frac{V_{dsatp}^2}{2}}$$



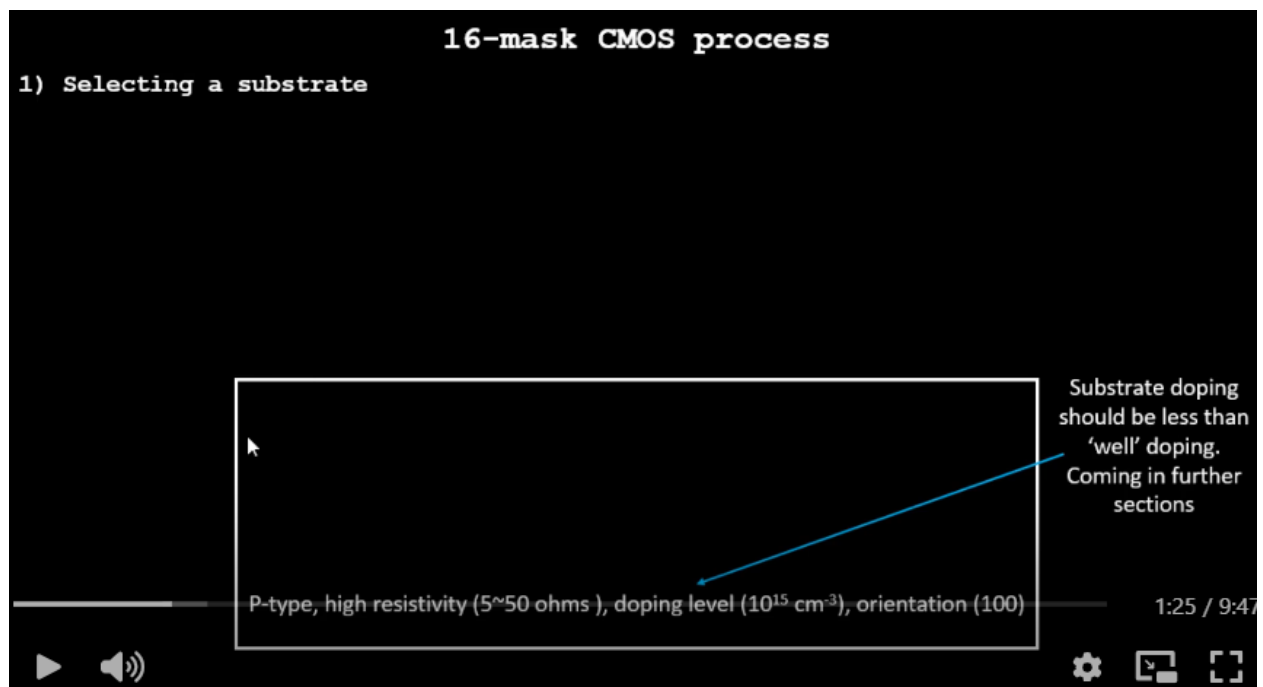


16-mask CMOS process.

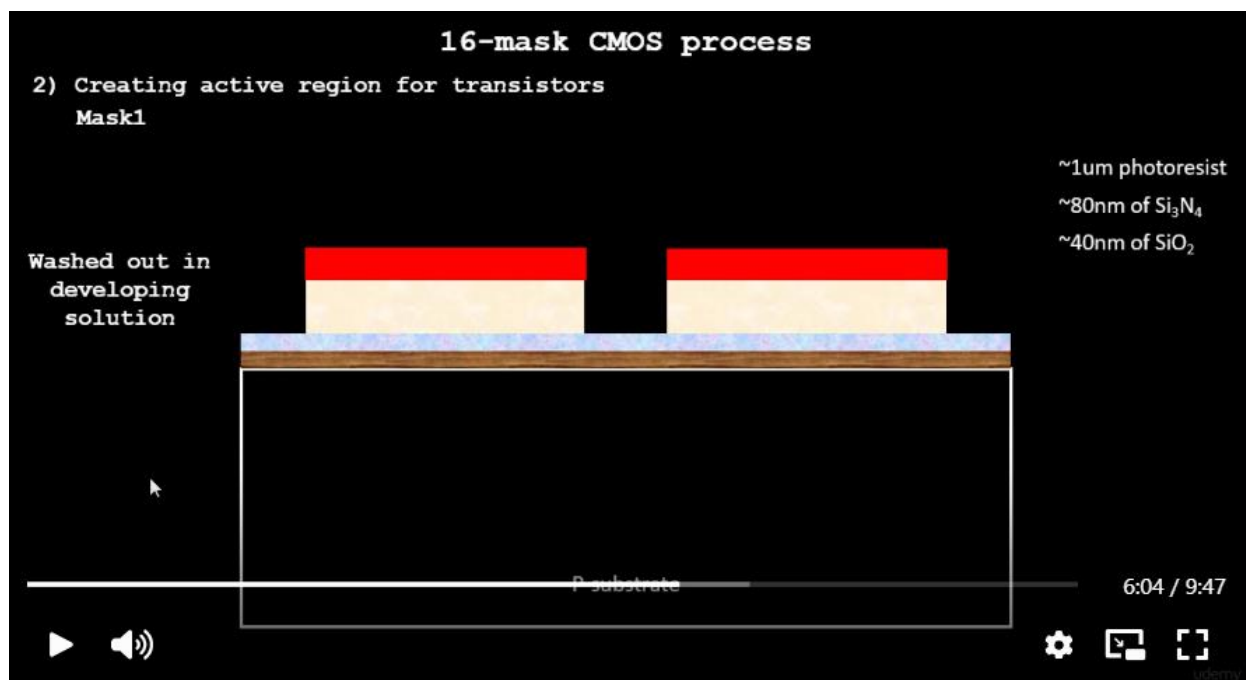
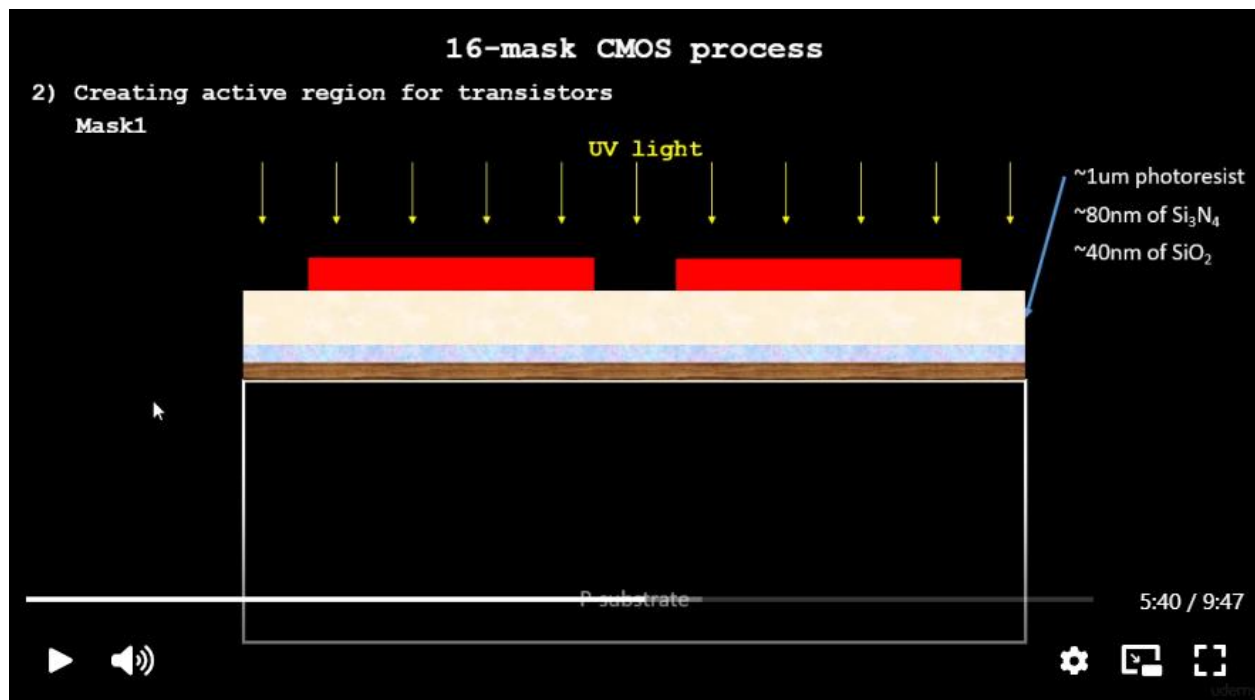
1) Selecting a substrate

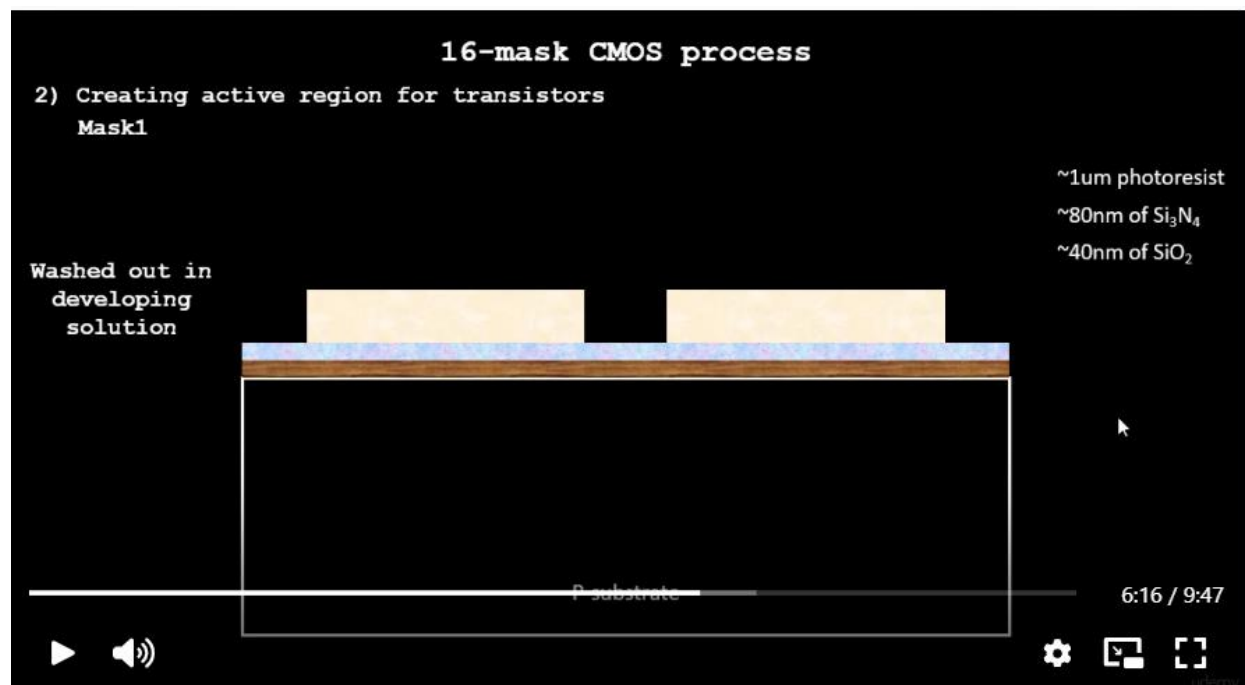
i) Doping level

Substrate doping should be less than 'well' doping. Coming in further sections.



2)





2) Creating active region for transistors

~40nm of SiO₂

▶ 🔊



udemy

2) Creating active region for transistors

~40nm of SiO₂

1D photonic crystal slab waveguide

▶ 🔊



LITERATURE

16-mask CMOS process

2) Creating active region for transistors

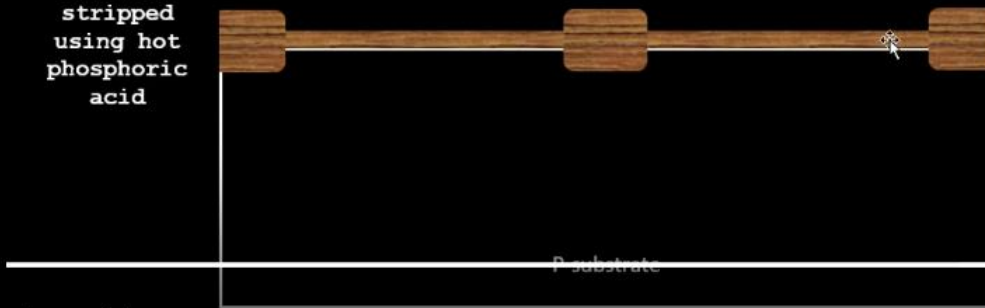
Mask1

~1 μ m photoresist

~80nm of Si_3N_4

~40nm of SiO_2

Si_3N_4
stripped
using hot
phosphoric
acid



9:28 / 9:47

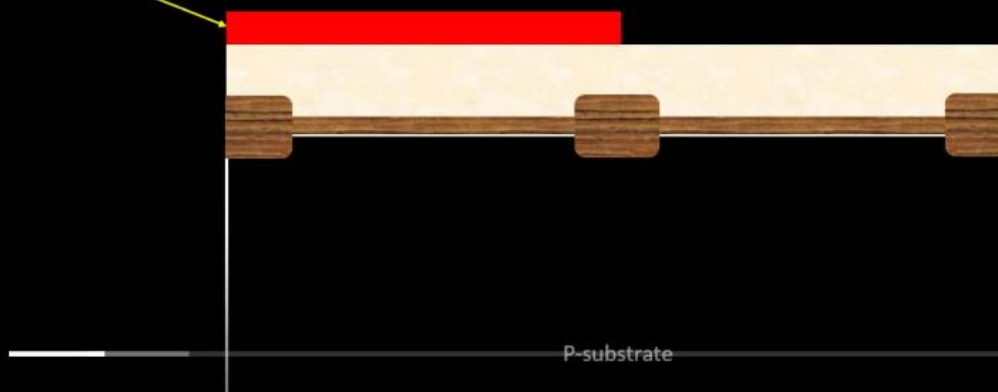


udemy

16-mask CMOS process

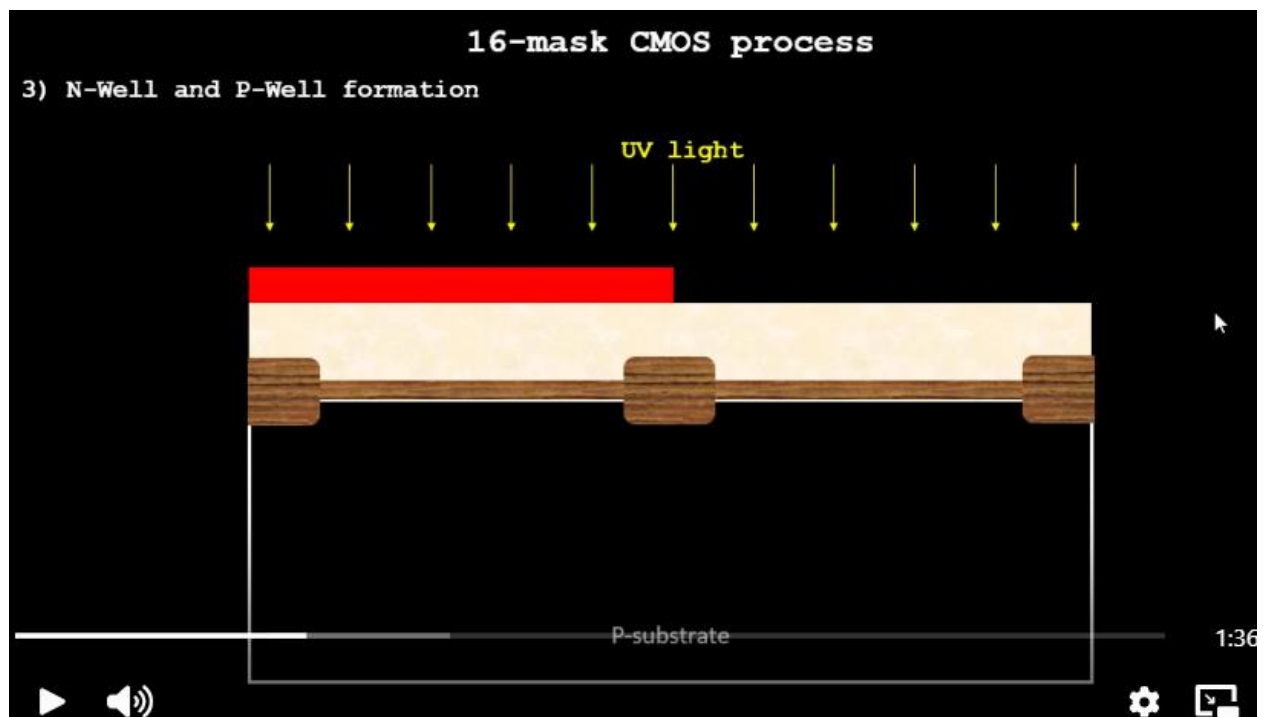
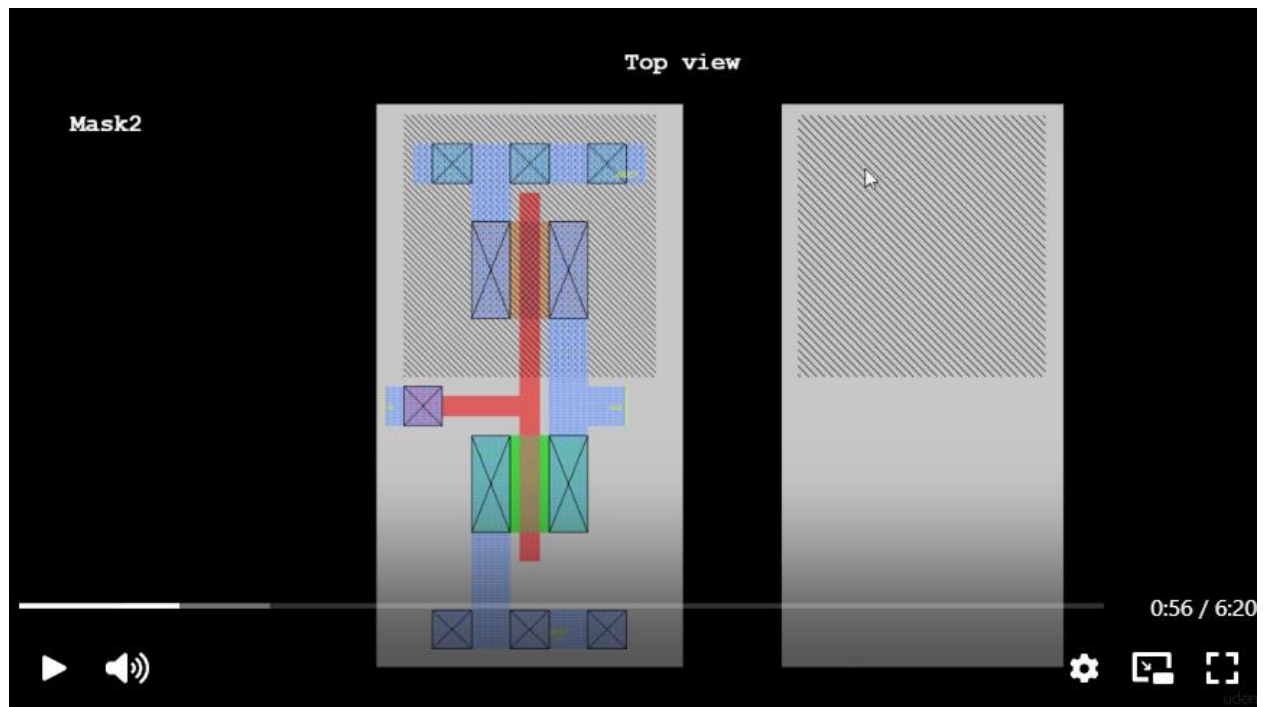
3) N-Well and P-Well formation

Mask2



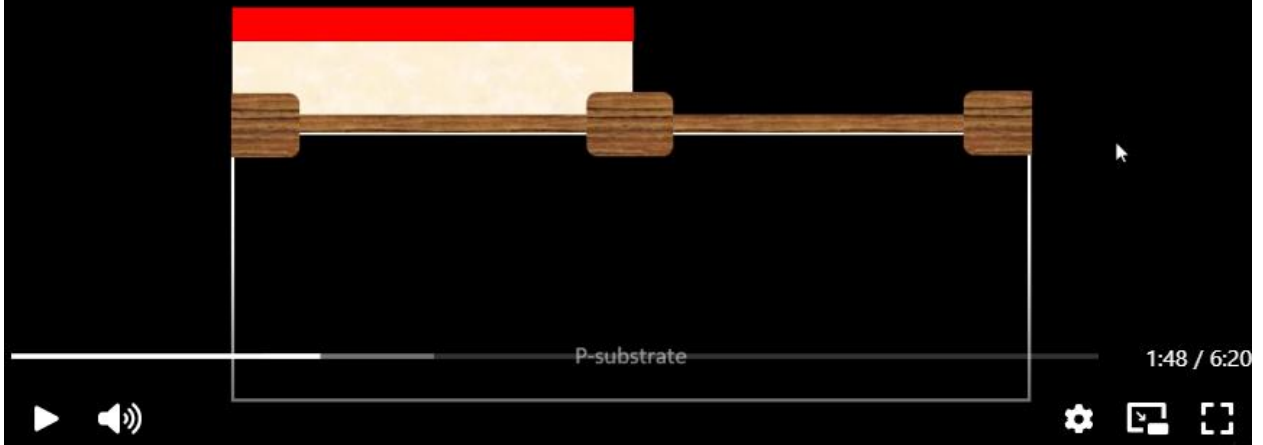
0:34 / 6:20





16-mask CMOS process

3) N-Well and P-Well formation



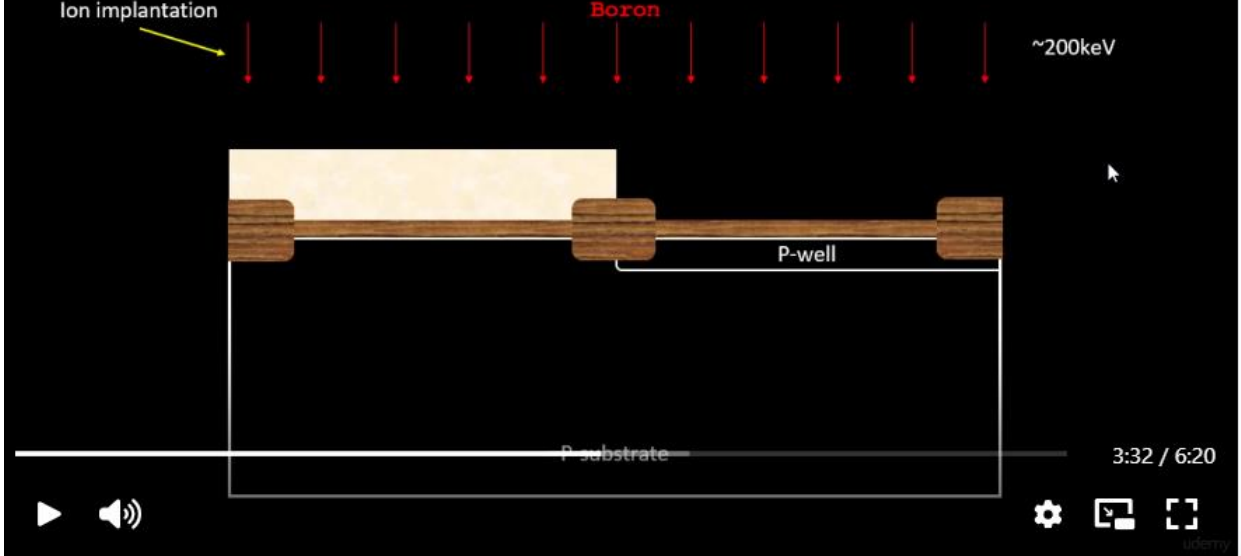
16-mask CMOS process

3) N-Well and P-Well formation

Ion implantation

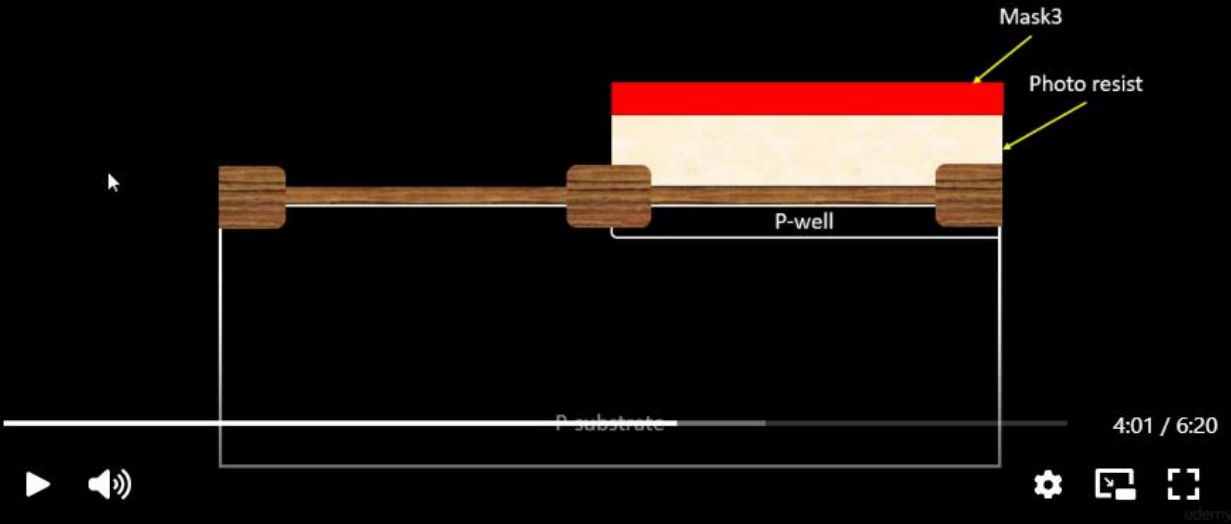
Boron

~200keV



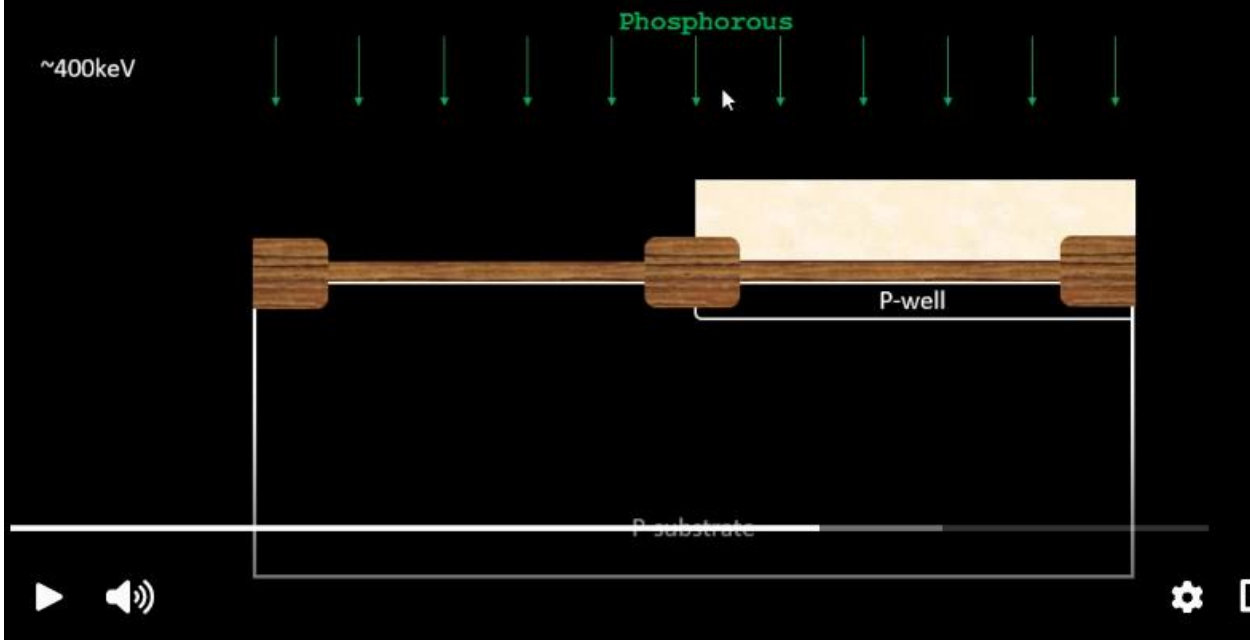
16-mask CMOS process

3) N-Well and P-Well formation



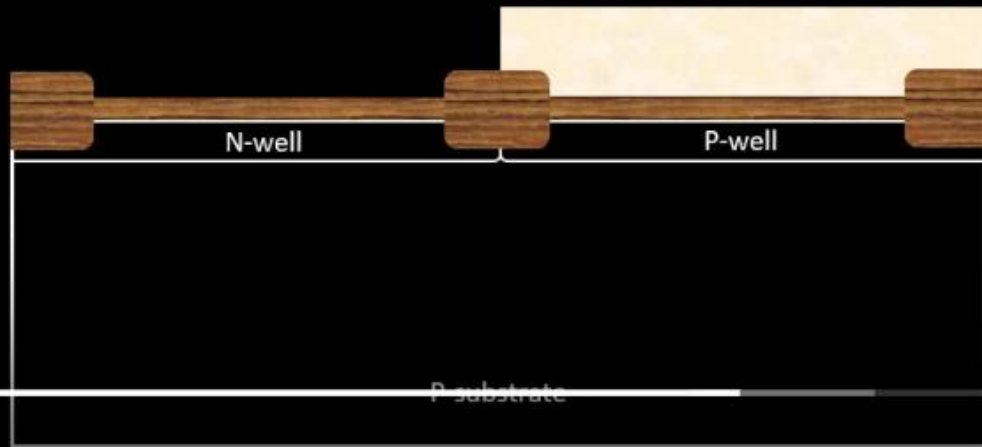
16-mask CMOS process

3) N-Well and P-Well formation



16-mask CMOS process

-Well and P-Well formation

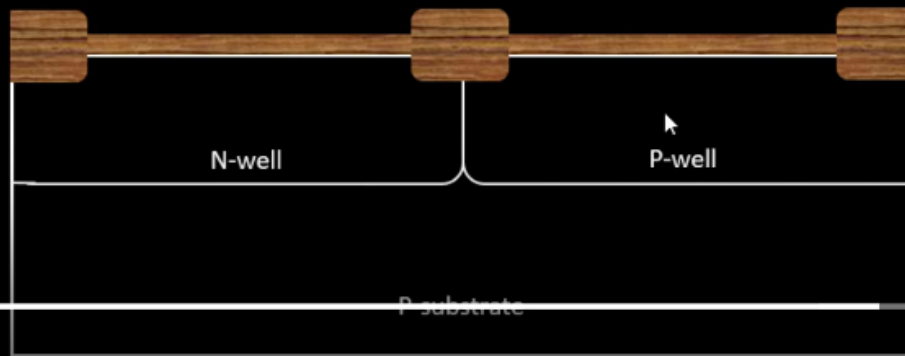


16-mask CMOS process

3) N-Well and P-Well formation

High temperature furnace

Drive-in diffusion



4) Formation of a gate.

Threshold Voltage Equation: *Snippet from "Circuit design and SPICE simulation" course*

$$V_t = V_{to} + \gamma(\sqrt{|-2\Phi_f + V_{sb}|} - \sqrt{|-2\Phi_f|})$$

Where
 V_{to} = Threshold voltage at $V_{sb} = 0$, and is a function of manufacturing process
 γ = body effect coefficient, expresses the impact of changes in body bias V_{sb} (Unit is $V^{0.5}$)
 Φ_f = Fermi Potential

$$\gamma = \frac{\sqrt{2qNA\epsilon_{si}}}{C_{ox}}$$

ϵ_{si} = relative permittivity of silicon = 11.7
 N_A = doping concentration
 q = charge of the electron
 C_{ox} = oxide capacitance

$$\Phi_f = -\Phi_T * \ln \frac{N_A}{n_i}$$

n_i = intrinsic doping parameter for the substrate

$V_{sb} = +ve$ value

0:54 / 8:07

udemy

Threshold Voltage Equation: *Snippet from "Circuit design and SPICE simulation" course*

$$V_t = V_{to} + \gamma(\sqrt{|-2\Phi_f + V_{sb}|} - \sqrt{|-2\Phi_f|})$$

Where
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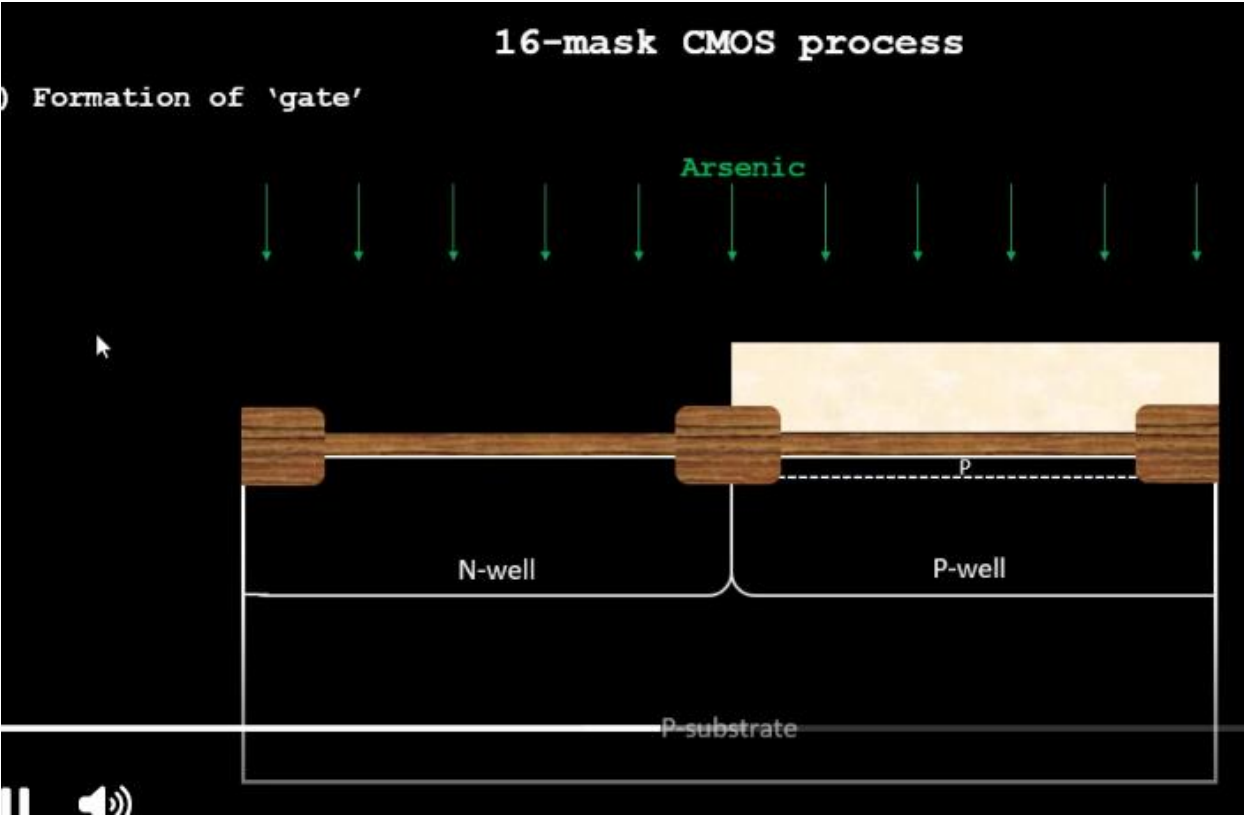
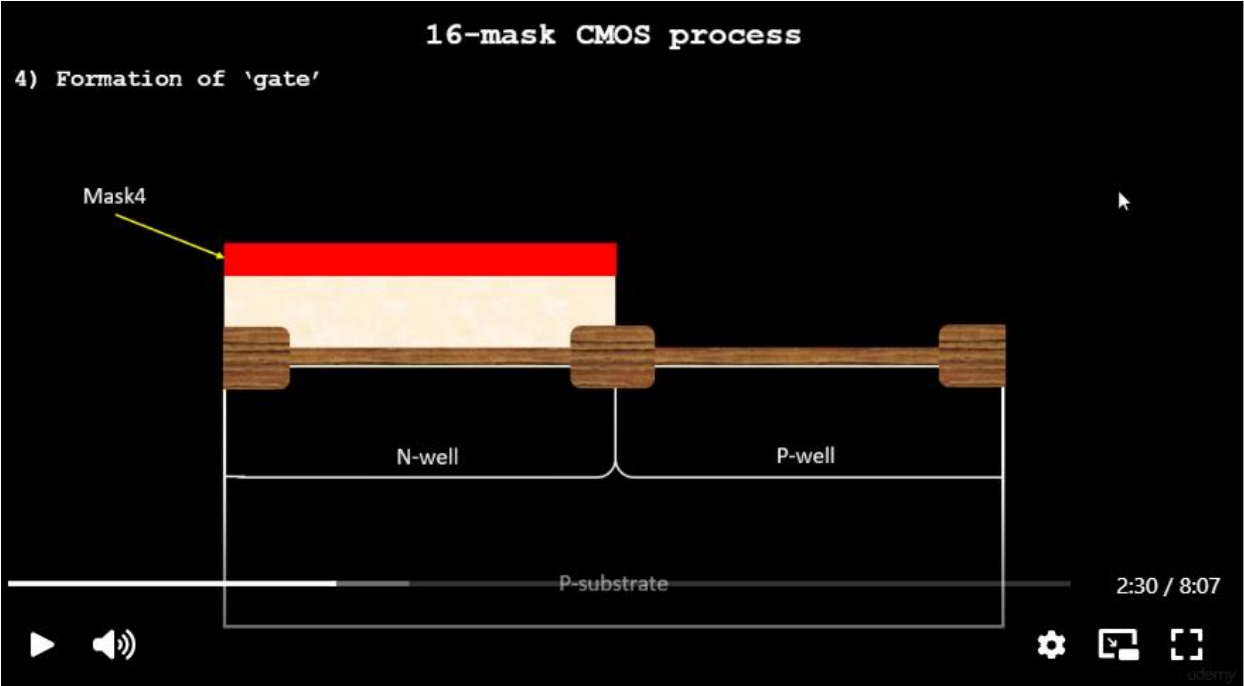
$$\Phi_f = -\Phi_T * \ln \frac{N_A}{n_i}$$

n_i = intrinsic doping parameter for the substrate

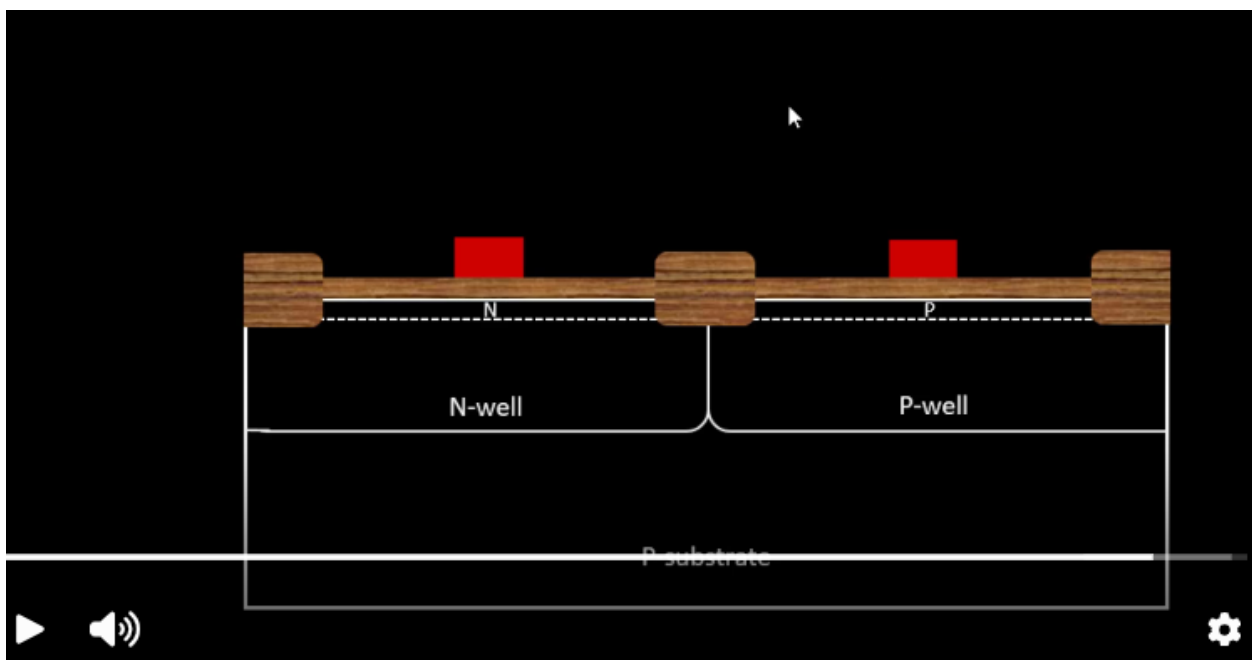
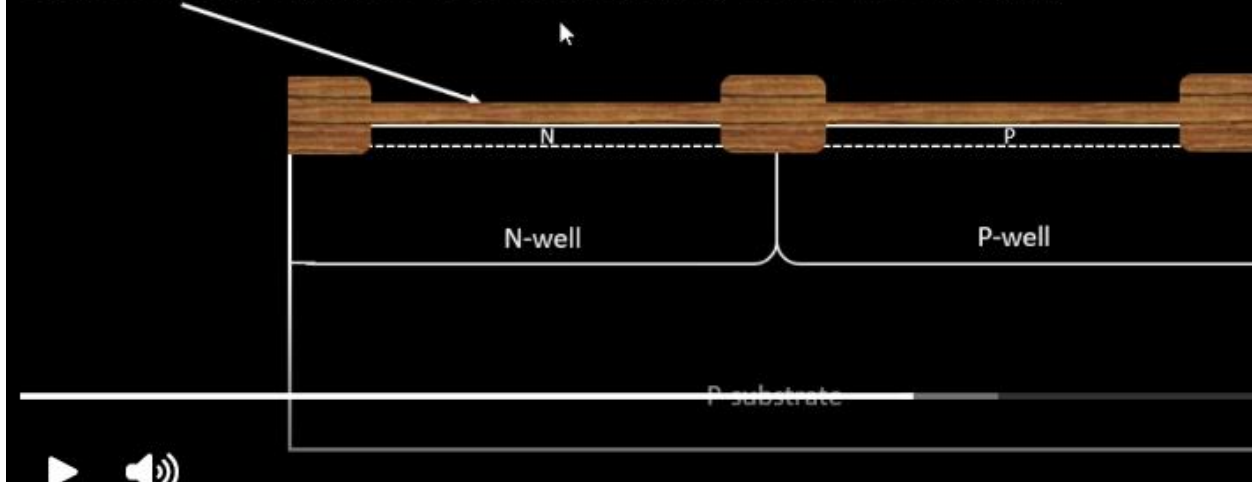
2 important terms for gate formation, as they control V_t

1:26 / 8:07

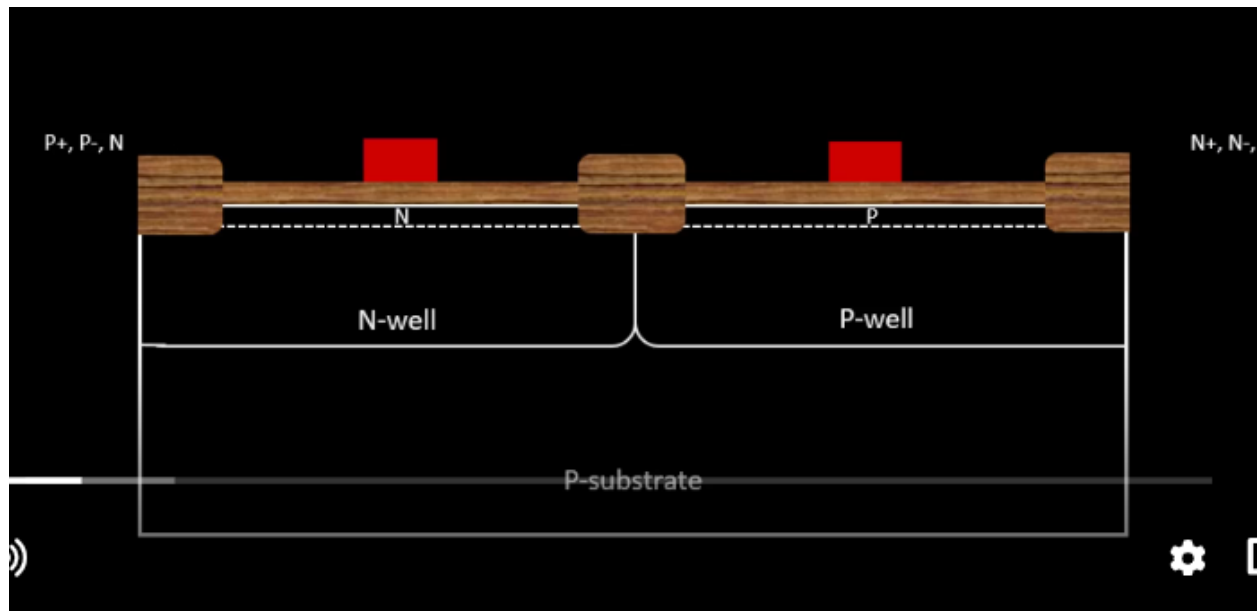
udemy



Original oxide etched/stripped using dilute hydrofluoric (HF) solution
Then re-grown again to give high quality oxide (~10nm thin)



5) Lightly doped drain



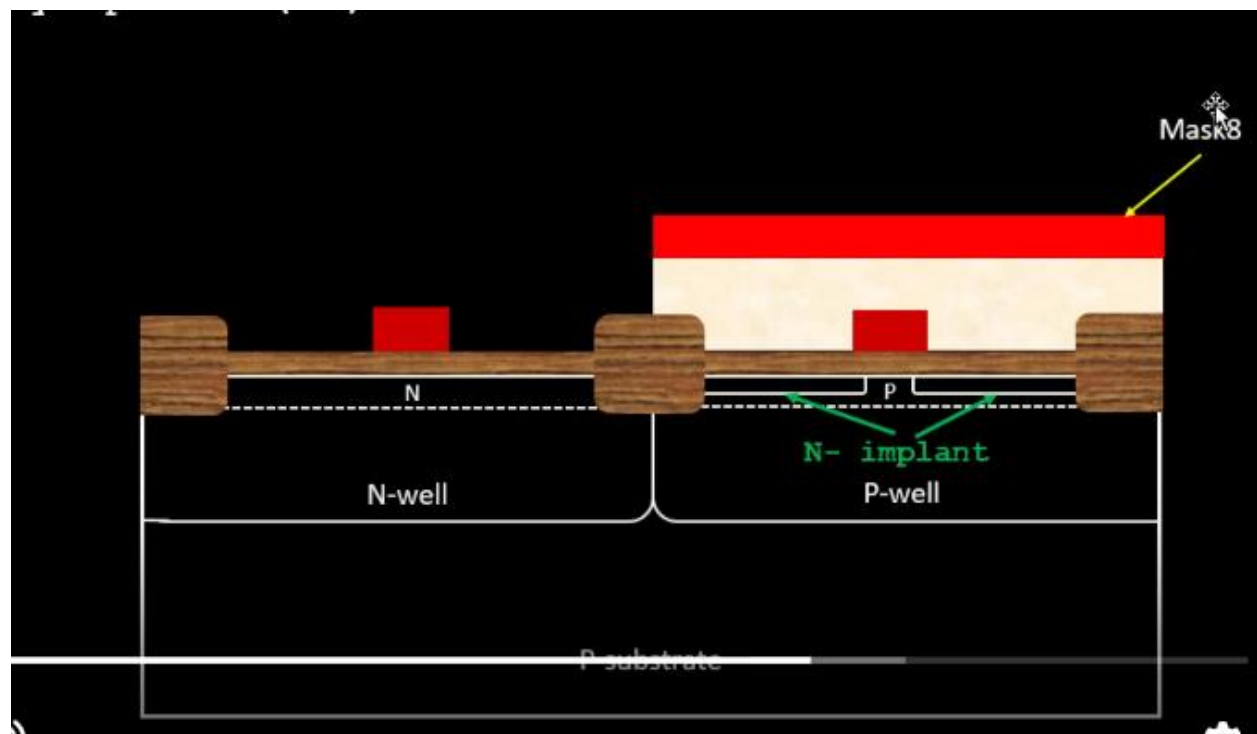
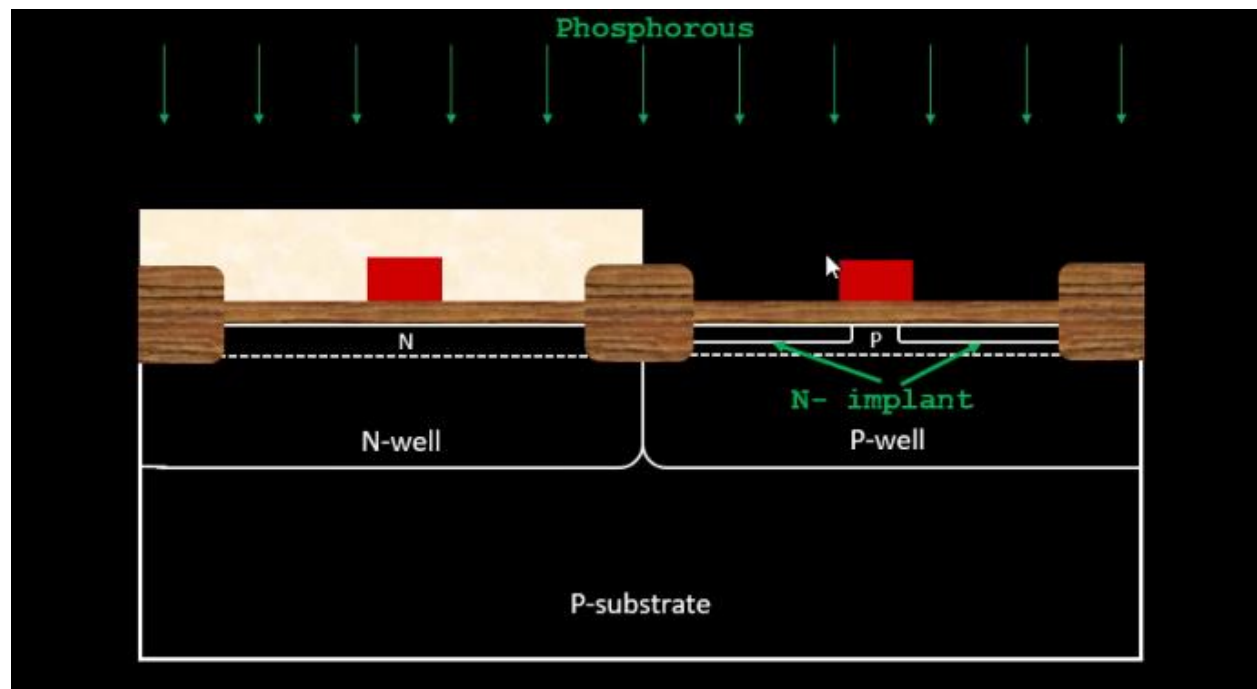
16-mask CMOS process

5) Lightly doped drain (LDD) formation

- 2 reasons for this
- Hot electron effect
 - Short channel effect

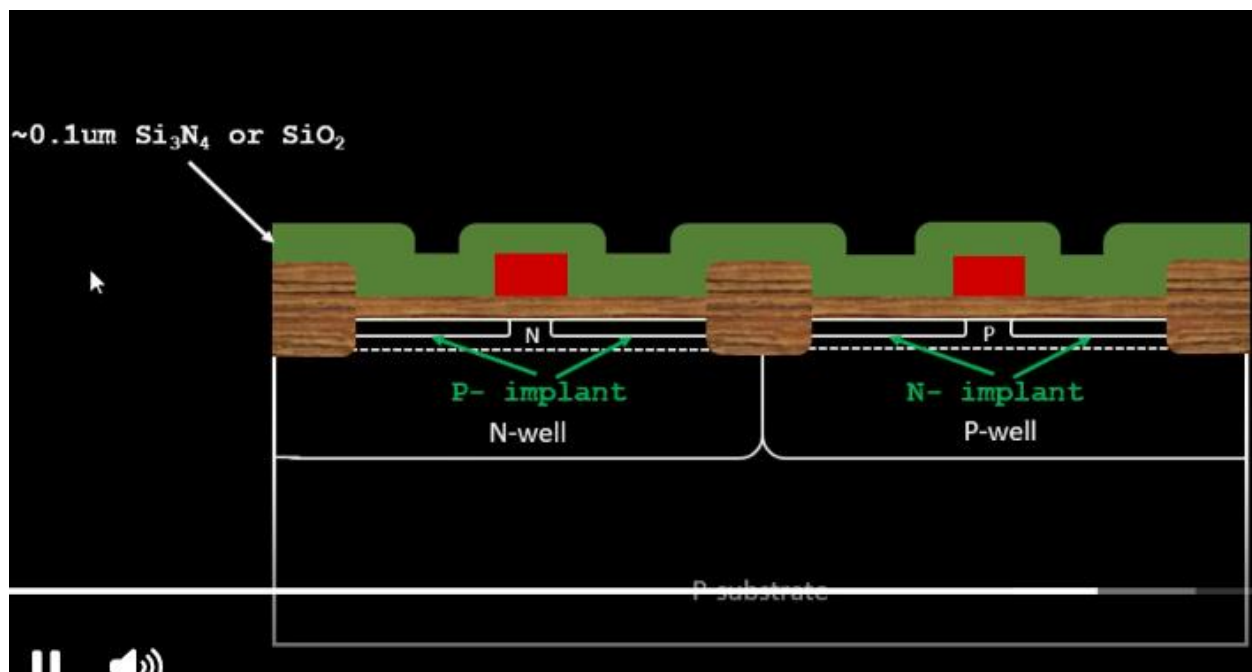
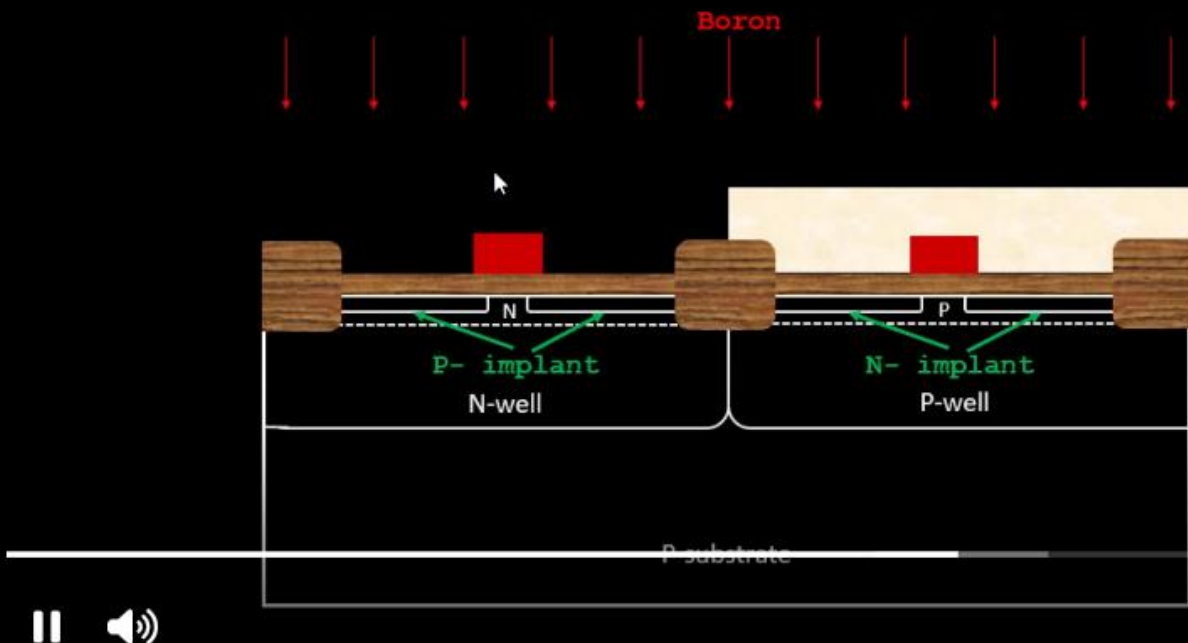
Electric field $E=V/d$
 High energy carriers break Si-Si bonds
 3.2eV barrier b/w Si conduction band
 SiO₂ conduction band

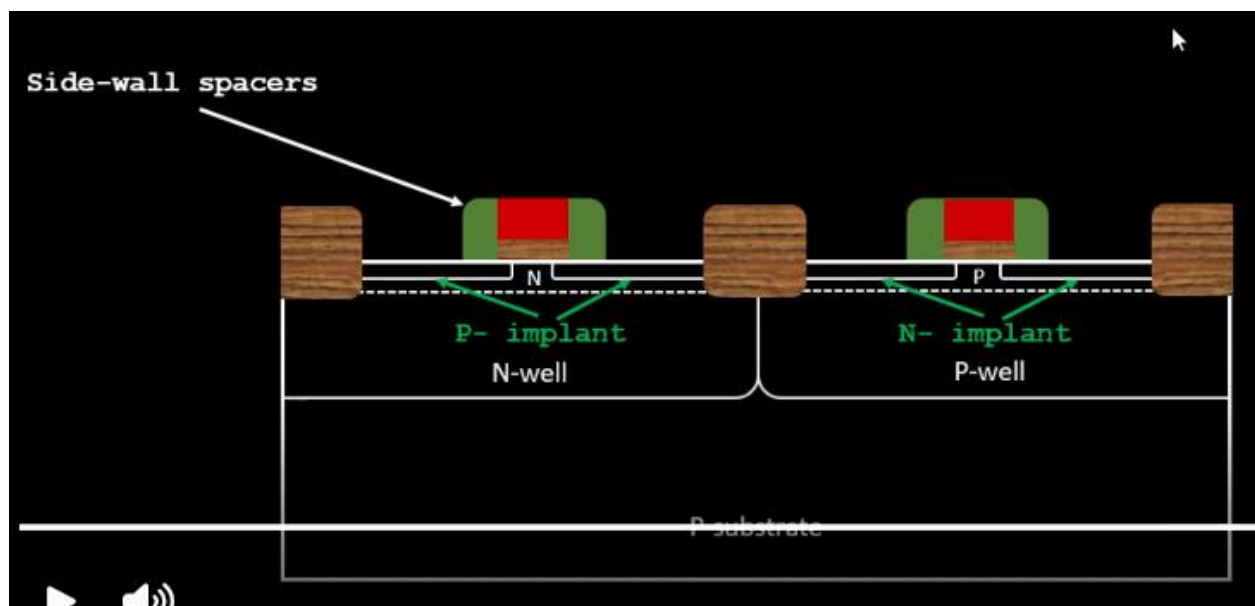
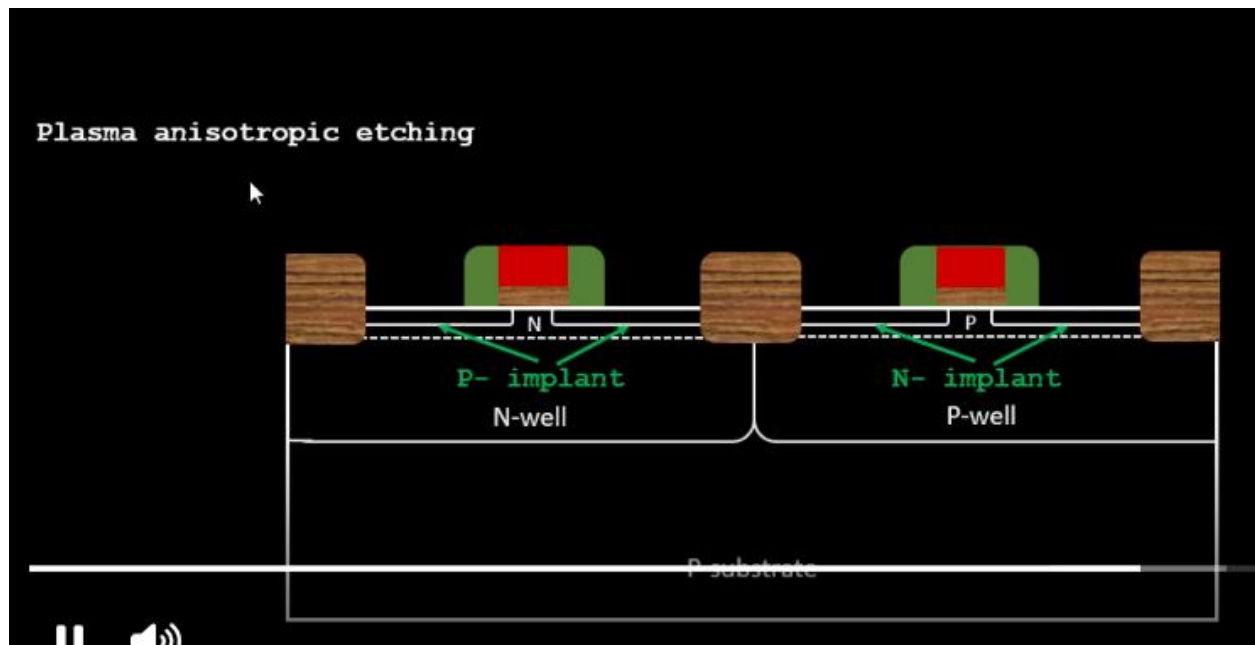




16-mask CMOS process

5) Lightly doped drain (LDD) formation





6)Source and the drain formation:

